Electronic Filing System (EFS) Data Electronic Patent Application Submission USPTO Use Only

EFS ID:

57249

Application ID:

10708649

METHOD FOR FORMING ROBUST

SOLDER INTERCONNECT

Title of Invention:

STRUCTURES BY REDUCING

EFFECTS OF SEED LAYER

UNDERETCHING

First Named Inventor:

Kamalesh Srivastava

Domestic/Foreign Application:

Domestic Application

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